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PATENT APPLICATION 7-12-02

RESPONSE UNDER 37 CFR §1.116  
EXPEDITED PROCEDURE  
TECHNOLOGY CENTER ART UNIT 2815

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Toshiyuki NAKAYAMA

Application No.: 09/582,351 ✓

Filed: August 11, 2000

For: SEMICONDUCTOR DEVICE AND METHOD OF MANUFACTURE THEREOF,  
CIRCUIT BOARD AND ELECTRONIC INSTRUMENT

Group Art Unit: 2815

Examiner: C. Chu

Docket No.: 106386

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR §1.116

Director of the U.S. Patent and Trademark Office  
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed February 27, 2002, the period for response being extended by the attached Petition for Extension of Time, please amend the above-identified application as follows:

IN THE CLAIMS:

Please replace claims 1 and 12 as follows:

1. (Twice Amended) A method of manufacture of a semiconductor device, comprising the steps of:
- providing an adhesive between a surface of a semiconductor chip having a plurality of electrodes on which said electrodes are provided and a surface of a substrate having a plurality of leads formed on which said leads are formed;